

ABSTRACT

A semiconductor device of the present disclosure includes a substrate having a recess, a first semiconductor element disposed in the recess, a first sealing layer disposed to cover a region including the recess in the substrate and sealing the first semiconductor element, and a second semiconductor element disposed to cover a surface in the first sealing layer opposite to the side of the substrate, the first sealing layer is composed of a cured product of a thermosetting resin composition, and an area of the recess is smaller than an area of the second semiconductor element.

Fig. 1